

Part Number: XLUY34D

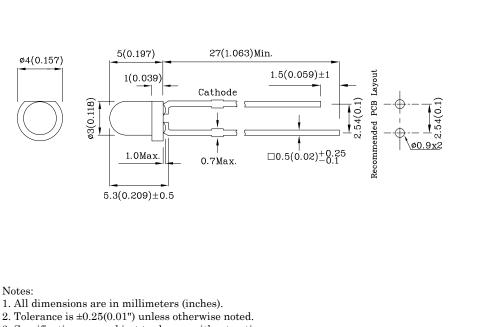
T-1 (3mm) SOLID STATE LAMP

Features

- Radial / Through hole package
- \bullet Reliable & robust
- Low power consumption
- Available on tape and reel
- \bullet RoHS Compliant



Package \$	Schematics
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3. Specifications are subject to change without notice.

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Absolute Maximum Ratings (T _A =25°C)	Yellow (GaAsP/GaP)	Unit			
Reverse Voltage	$V_{\rm R}$	5	V		
Forward Current	$I_{\rm F}$	30	mA		
Forward Current (Peak) 1/10 Duty Cycle 0.1ms Pulse Width	ifs	140	mA		
Power Dissipation	\mathbf{P}_{D}	75	mW		
Operating Temperature	$T_{\rm A}$	-40 ~ +85			
Storage Temperature	Tstg	-40 ~ +85	°C		
Lead Solder Temperature [2mm Below Package Base]	260°C For 3 Seconds				
Lead Solder Temperature [5mm Below Package Base]	260°C For 5 Seconds				

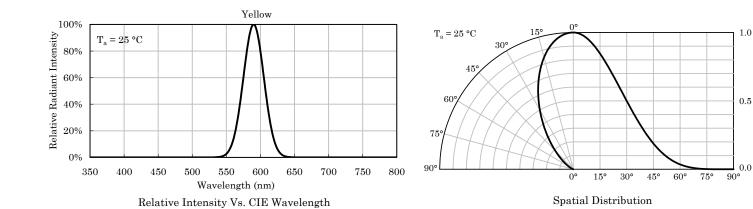
A Relative Humidity between 40% and 60% is recommended in ESD-protected work areas to reduce static build up during assembly process (Reference JEDEC/JESD625-A and JEDEC/J-STD-033)

Operating Characteristics (T _A =25°C)		Yellow (GaAsP/GaP)	Unit
Forward Voltage (Typ.) (I _F =10mA)	V_{F}	1.95	v
Forward Voltage (Max.) (I _F =10mA)	V_{F}	V _F 2.4	
Reverse Current (Max.) $(V_R=5V)$	I_R	10	μА
Wavelength of Peak Emission CIE127-2007*(Typ.) (I _F =10mA)	λP	590*	nm
Wavelength of Dominant Emission CIE127-2007*(Typ.) (I _F =10mA)	λD	588*	nm
Spectral Line Full Width At Half-Maximum (Typ.) (I _F =10mA)	$ riangle \lambda$	35	nm
Capacitance (Typ.) (V _F =0V, f=1MHz)	С	20	pF

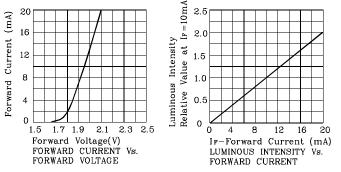
Part Number	Emitting Color	0	Lens-color	Luminous CIE127 (I _F =10 m	7-2007* 0mA)	Wavelength CIE127-2007* nm λP	Viewing Angle 20 1/2
				min.	typ.		
XLUY34D	Yellow	GaAsP/GaP	Yellow Diffused	8*	14*	590*	60°

*Luminous intensity value and wavelength are in accordance with CIE127-2007 standards.

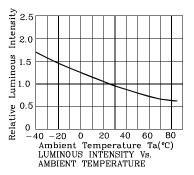




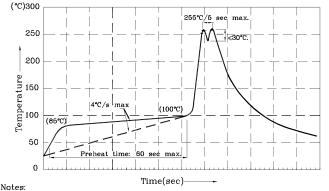
♦ Yellow



50 (mA) 40 Current 30 20 Forward 10 0 ō 20 40 60 100 80 Ambient Temperature Ta(°C) FORWARD CURRENT DERATING CURVE



Wave Soldering Profile For Thru-Hole Products (Pb-Free Components)



I.Recommend pre-heat temperature of 105°C or less (as measured with a thermocouple attached to the LED pins) prior to immersion in the solder wave with a maximum solder bath temperature of 260°C
2.Peak wave soldering temperature between 245°C ~ 255°C for 3 sec

(5 sec max).

3.Do not apply stress to the epoxy resin while the temperature is above 85° C. 4.Fixtures should not incur stress on the component when mounting and

during soldering process. 5.SAC 305 solder alloy is recommended.

6. No more than one wave soldering pass.

Remarks:

If special sorting is required (e.g. binning based on forward voltage, luminous intensity / luminous flux, or wavelength),

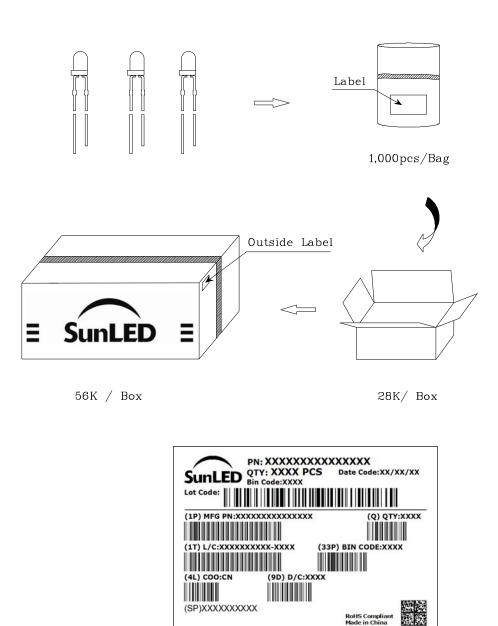
the typical accuracy of the sorting process is as follows:

- 1. Wavelength: +/-1nm
- 2. Luminous Intensity / Luminous Flux: +/-15%
- 3. Forward Voltage: +/-0.1V

Note: Accuracy may depend on the sorting parameters.



PACKING & LABEL SPECIFICATIONS



TERMS OF USE

- 1. Data presented in this document reflect statistical figures and should be treated as technical reference only.
- 2. Contents within this document are subject to improvement and enhancement changes without notice.
- 3. The product(s) in this document are designed to be operated within the electrical and environmental specifications indicated on the datasheet.
- User accepts full risk and responsibility when operating the product(s) beyond their intended specifications. 4. The product(s) described in this document are intended for electronic applications in which a person's life is not reliant upon the LED. Please
- consult with a SunLED representative for special applications where the LED may have a direct impact on a person's life.
- 5. The contents within this document may not be altered without prior consent by SunLED.
- 6. Additional technical notes are available at <u>https://www.SunLEDusa.com/TechnicalNotes.asp</u>